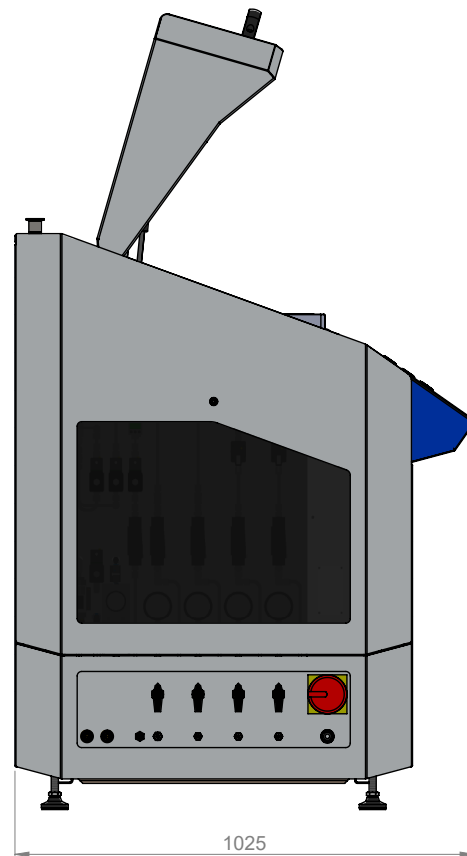
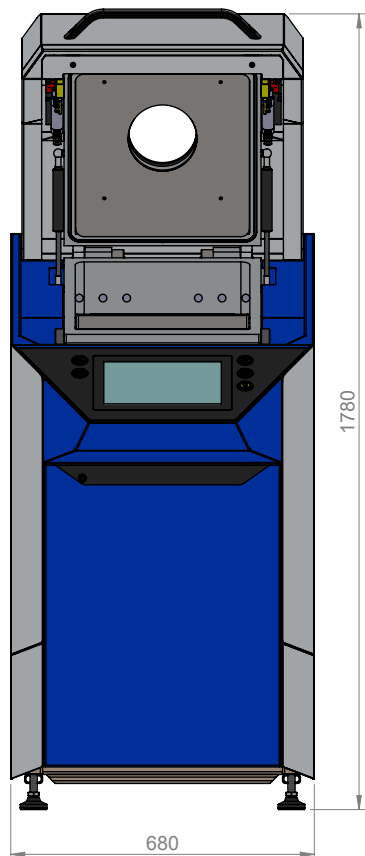


VS 320

The next generation of Vacuum Soldering Systems





Technical Data

| | |
|-----------------------------|--------------------------------------|
| Plate size: | 320 x 320 mm ² |
| Chamber height: | 100 mm |
| Max. soldering temperature: | 450 °C |
| Heating- / Coolingramp: | 2 K/s |
| Max. load: | 15 kg |
| Process atmosphere: | N ₂ |
| | N ₂ H ₂ (95/5) |
| | HCOOH |
| | H ₂ (up to 100%) |
| | Plasma (Microwave) |
| Power supply: | 400 V / 32 A |
| Cooling Water: | 20 slm |

Features

| |
|---|
| Process-Control via separate thermocouples |
| Graphical overview of process components |
| Digital manual integrated in the software |
| Maintenance reminder |
| Proposal for changing necessary components at the end of lifetime |
| Power monitoring to detect defective heating rods |
| Monitoring of energy consumption (Industry 4.0) |
| Optional manipulation inside the chamber |
| Optional sintering device SP 60 |
| Optional MES protocol: SECS/GEM, OPC-UA, etc. |